IN THE SPECIFICATION:

Please replace the paragraph starting at page 11, line 20 and ending at page 12, line 12 with the following paragraph:

As can be seen from Figure 1, the contact structure 10 between the chip terminal area 16 and the coil wire end 15 is made up of three components, namely an intermediate metallization 18, a spacing metallization 19 and a conductive adhesive compound 20. In the present case, a nickel-containing and gold-containing alloy that can be applied adhesively to the chip terminal area 16, for example, in an electroless metal deposition process is used for the intermediate metallization 18 applied directly to the aluminum terminal area 16 of the chip 11. The spacing metallization 19 is, on the other hand, formed from a conventional solder alloy, for example a ~~low-m,elting~~ low-melting lead/tin alloy. In the contact structure 10 shown in Figure 1, not only the electrically conducting contact between the spacing metallization 19 and the coil wire end 15, but also the mechanical joint between the spacing metallization 19 and the coil wire end 15 is made by means of the adhesive compound 20. At the same time, the electrical connection is achieved by means of electrically conductive particles contained in the adhesive compound 20 and the mechanical joint is achieved by means of the adhesive forces acting in the adhesive compound.